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## \*BIBDATASHEET\*

Bib Data Sheet

CONFIRMATION NO. 80

SERIAL NUMBER 10/803,782	FILING DATE 03/18/2004  RULE	CLASS 438	GROUP ART UNIT 2814	ATTORNEY DOCKE NO. 36080.00802
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## APPLICANTS

Edward G. Combs, Foster, CA;

Robert P. Sheppard, Red Bluff, CA;

Tai Wai Pun, Hong Kong, HONG KONG; Hau Wang Ng, Hong Kong, HONG KONG;

Chun Ho Fan, Hong Kong, HONG KONG;

Neil Robert McLellen, Hong Kong, HONG KONG;

## \*\* CONTINUING DATA \*\*\*\*\*

AC This application is a DIV of 09/902,878 07/11/2001 PAT 6,734,552

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

AC None

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 08/04/2004

Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY CA	SHEETS DRAWING 11	TOTAL CLAIMS 20	INDEPENDENT CLAIMS 3
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged Examiner's Signature <i>James Chambliss</i> Initials				

## ADDRESS

27171  
 MILBANK, TWEED, HADLEY & MCCLOY LLP  
 1 CHASE MANHATTAN PLAZA  
 NEW YORK, NY  
 10005-1413

## TITLE

Method of manufacturing an enhanced thermal dissipation integrated circuit package

FILING FEE  RECEIVED 1059	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____
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